



Docket No.: AB-1111 US

March 23, 2001

Box Patent Application
Commissioner For Patents
Washington, D. C. 20231

Enclosed herewith for filing is a patent application, as follows:

Inventors: Seong Min Seo, Young Suk Chung, Jong Sik Paek, Jae Hun Ku, Jae Hak Yee
Title: Semiconductor Package Including Stacked Chips

<u>X</u>	Return Receipt Postcard;
<u>X</u>	This Transmittal Letter (in duplicate);
<u>21</u>	pages Specification (not including claims);
<u>10</u>	pages Claims;
<u>1</u>	page Abstract;
<u>5</u>	Sheets of Drawings (Figs. 1, 2A, 2B, 3A, 3B, 4A, 4B, 5A, 5B);
<u>2</u>	pages Declaration For Patent Application and Power of Attorney (signed by Seong Min Seo, Young Suk Chung, Jong Sik Paek);
<u>1</u>	Page Recordation Form Cover Sheet (in duplicate);
<u>3</u>	Pages Assignment (signed by Seong Min Seo, Young Suk Chung, Jong Sik Paek); and
<input checked="" type="checkbox"/>	Other: Certified copy of Korean Priority Document, 2000-15305, filed 3/25/00.

CLAIMS AS FILED

For	Number Filed		Number Extra		Rate		Basic Fee
Total Claims	33	-20 =	13	x	\$ 18.00	=	\$ 234.00
Independent Claims	3	-3 =	0	x	\$80	=	\$ 0.00
<input type="checkbox"/>	Fee of _____ for the first filing of one or more multiple dependent claims per application						\$
<input type="checkbox"/>	Fee for Request for Extension of Time						\$

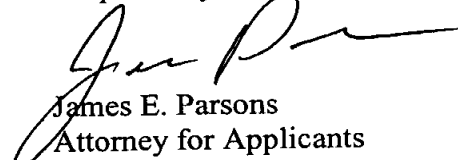
Please make the following charges to Deposit Account 19-2386:

- ☒ Total fee for filing the patent application in the amount of \$ 944.00
☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account 19-2386.

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Respectfully submitted,


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